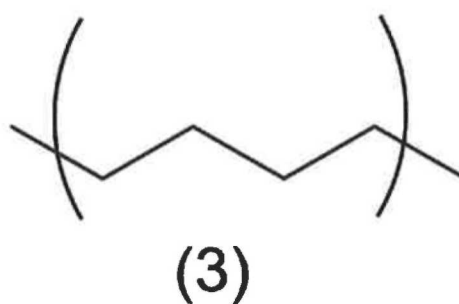
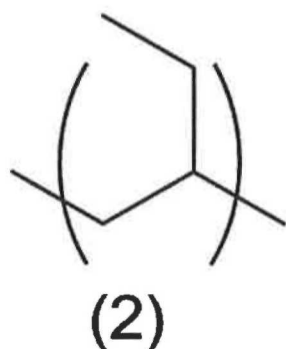
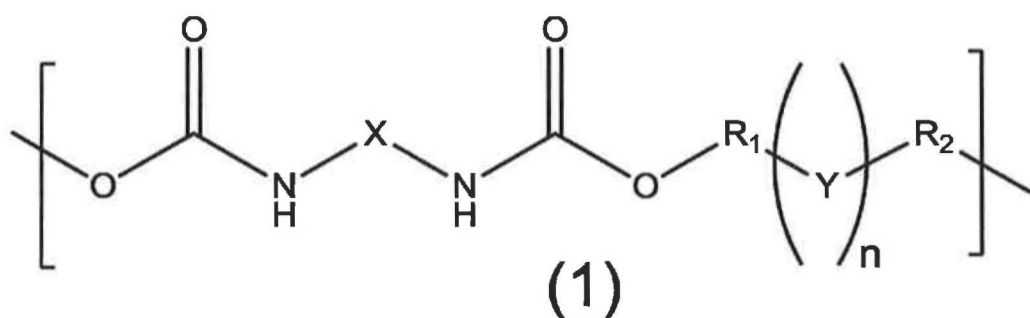


ABSTRACT

PHOTOSENSITIVE RESIN COMPOSITION AND ADHESIVES COMPOSITION

There is provided a novel photosensitive resin composition. A photosensitive resin composition comprising a polymer having a repeating structural unit of the following Formula (1):



(wherein R_1 and R_2 are each independently a single bond, a methylene group, or an ethylene group, Y is an alkylene group of Formula (2) or a combination of the alkylene group of Formula (2) with an alkylene group of Formula (3), n is an integer of 1 to 110, and X is a divalent aliphatic hydrocarbon group, a divalent alicyclic hydrocarbon group, or a divalent aromatic hydrocarbon group) and a (meth)acryloyl group at both ends, a bifunctional (meth)acrylate compound, a polyfunctional thiol compound, a photo-radical generator and an organic solvent, and then the bifunctional (meth)acrylate compound contained in an amount of 5% by mass to 50% by mass and the polyfunctional thiol compound is contained in an amount of 0.1% by mass to 10% by mass, relative to the content of the polymer.